

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

APPLICANTS: Koichi HIRAMATSU et al.

SERIAL NO. : 09/880,925

FILED : JUNE 15, 2001

FOR : MOLDING CLAMPING APPARATUS AND MOLD  
CLAMPING METHOD

ART UNIT : 1722

ASSISTANT COMMISSIONER OF PATENTS  
Washington, D.C. 20231

**CLAIM TO CONVENTION PRIORITY UNDER 35 U.S.C. § 119**

SIR:

On July 11, 2001, the Applicant's filed a Claim to Convention Priority Under 35 U.S.C. § 119, referencing the Japanese Patent Applications identified below. This filing has attached hereto ribbon-sealed certified copies of the cited applications. The Convention Priority Date of Japanese Patent Application No. 2000-181314 was filed on June 16, 2000, Japanese Patent Application No. 2001-092764 was filed on March 28, 2001, Japanese Patent Application No. 2001-156393 was filed on May 25, 2001, and Japanese Patent Application No. 2001-156394 was filed on May 25, 2001 and was claimed in the specification of U.S. Serial No. 09/880,925 filed on June 15, 2001. To complete the claim to the Convention Priority Date of said Japanese Patent Applications, certified copies thereof are submitted herewith.

Respectfully submitted,



Mark H. Neblett  
Registration No. 42,028

Dated: August 29, 2001  
KENYON & KENYON  
1500 K Street, N.W., Suite 700  
Washington, DC 20005  
Tel: (202) 220-4200  
Fax: (202) 220-4201